

Final Product Change Notification

202407029F01: PCA9555APW Wire Conversion from Gold to Copper

Note: This notice is NXP Company

Proprietary.

Issue Date: Aug 05, 2024 Effective Date: Nov 08, 2024

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Management summary

NXP will change the wire for the bonding process of the PCA9555APW product, from gold to copper for improved reliability and manufacturing logistics. This will align the manufacturing process and flow of this product to industry standard.

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware []Other				

Notification Overview

Description

ATBK will convert to copper wire for this product.

Reason

Copper wire will improve overall product reliability and reduce logistics risks in production, by moving the product, to standard, current production materials.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Nov 10, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 04, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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